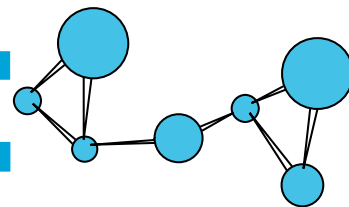


Thermoset Technology UPDATE

Summer 2002



A Biannual Newsletter Published by the Thermoset Technology Division of the Society of the Plastics Industry, Inc.

THE FALL TTD CONFERENCE

Hubert Monteiro, Royce International

The Fall Conference of the Thermoset Technology Division promises to be a very interesting one. Scheduled for October 13-15, 2002 in Cincinnati, it affords participants the opportunity of attending the Coil Winding Show, which will take place in the same city on October 16-18.

The papers to be presented at our Conference will cover a wide spectrum of topics. There will be two papers on adhesives and adhesion: one on Plasma Surface Treatment to enhance adhesion by Stephen Kaplan and another on Structural Adhesive Bonding by Scott Durso of Lord Corporation. The problem of crystallization in epoxy resins and the use of reactive diluents to overcome it will be dealt with by P.K. Dubey and H.K. Soni of Thai Epoxy. Waterborne coatings are the focus of attention today in the context of reducing environmental pollution. C. Hegedus of Air Products will discuss this issue by introducing some new epoxy-acrylic coatings. Philip Papoojian of Merco makes a quest for standardisation of Thermal Conductivity measurements, an important consideration in designing epoxy cast electrical and electronic components which generate heat.

There will be other papers as well, theoretical, practical and commercial to interest the thermoset formulator. ♦

ERFD Report Renamed

The ERFD Report has a new name! The name of this newsletter has been changed to reflect the new name of the Epoxy Resin Formulators Division – the Thermoset Technology Division. The name change was made in fall of 2001 to reflect its expanded interests, scope and participation.

Now known as the Thermoset Technology Division (TTD), the business has as its goal the advancement of the thermoset formulating industry through the development and distribution of information products that help its members and protect and improve their businesses while promoting the value of thermoset materials.

Organized as the ERFD in 1957, the TTD is the only organization dedicated solely to serve the needs and interests of thermoset formulators. Member companies include raw material suppliers, thermoset formulators, equipment manufacturers, consulting firms and academic institutions. This membership reflects the multitude of end uses for formulated thermoset products, including adhesives, coatings, civil engineering applications, electrical laminates, composites, tooling, castings and moldings. ♦

Formulator's Section Luncheon

by John Ulcar, Crosslink Technology, Inc.

The formulator attendees had another "animated" discussion regarding future conferences. The economic climate has changed the travel and expense patterns within the country and our industry. To address this issue and to meet the needs of our members, we had agreed to propose the following

changes to our conferences.

1. We should have only one conference per year (for the foreseeable future).
2. They should be held in the spring of each year.
3. The conference agenda should be changed to three half day

sessions with scheduled networking activities in the afternoon.

4. The general preferred locations were cities in the east.

These changes reflect the needs of the members to maximize their benefits and will be presented to the executive for future conferences. ♦

Chairperson's COLUMN



John Ulcar, Crosslink
Technology, Inc.

Thoughts on
Excellence from Walt
Disney:

1. Think tomorrow (make today an investment in tomorrow).
2. Free up your imagination (we can usually do more than we ever thought we could).
3. Strive for lasting quality (don't cut corners; do everything the best you can the first time).
4. Stick-to-it-ivity (don't quit too soon; hang in there).
5. Have fun!

(cited in "Bits and Pieces")

I thought these words from Walt Disney were appropriate due to our recent conference location, and especially, because they ring so true for the Thermoset Technology Division and its members.

For the many years that I have been a member of ERF, and now TTD, the

executive has always struggled with the question: What are the benefits of our 'trade association'?

Inasmuch as the benefits to individual companies and the group change with the needs of any given time (e.g. standardizing epoxy test methods through round robin testing many years ago, through to EPA and epoxy testing in the early nineties), there has always been the underlying theme of human contact and communication.

All our contacts are investments in tomorrow, are a conduit to improving the quality of our companies and the

epoxy and urethane industry as a whole. And there is nothing wrong with having fun while we are working through this process.

In this day and age, much communication can be accomplished quickly and efficiently with all our high tech tools available to us, and they are valuable tools. What they do not provide is the spontaneity of group and individual dynamics. Some of the brightest moments and revelations have come during the give and take, normally, when several attendees combine their thoughts and question patterns in ways that would not be possible using inanimate means of communication or even during

individual company sales calls.

I have had speakers comment, after their presentation, that they had learned more about their own subject, during their session, than they had ever expected. As well, I have had attendees tell me that they came to the conference for a particular paper, but were surprised at information they gleaned from the other topics they believed they had interest in hearing.

It is our networking opportunities through the friendly atmosphere that we provide that makes our division excellent... Walt would have been proud. ❖

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The Thermoset Technology Update welcomes comments and suggestions from members. Contact Allen Weidman, Executive Director, SPI, 1801 K Street, N.W., Suite 600K, Washington, D.C. 20006-1301, Phone: (202) 974-5233, Fax: (202) 293-0005.

TTD Spring 2002 Conference Wrap-Up

By John Ulcar, Crosslink Technology, Inc.

Our TTD Spring Conference in Orlando once again continued our tradition of quality papers and networking opportunities for our participants from the U.S., Mexico, Canada and the Pacific Rim. Warm weather and blue skies complimented our meeting agenda, which was filled with many interesting papers.

Some of the highlights were:

- A presentation from and OEM: Delphi Automotive Systems. Brian Knouff presented an award winning paper on, "Automotive Design and Processing objectives with Thermoset Materials"
- Academic papers from Virginia Polytechnic Institute and State University
- Supplier papers from Bayer, Cognis, Huntsman, Rebus, Air Products, Fluoro-Seal and Underwriters Laboratories. Julie Baum from Air Products

presented "Epoxy Industry Statistics"

- Our guest speaker, Roy H. Johanson, Jr., from NASA kept us all riveted with his insights into the space program.... and beyond!
- The Product Stewardship program was not to be outdone; their guest speaker was also from Disney World speaking on the regulatory issues that they deal with in their day-to-day operations.
- During our Monday reception, the attendees were able to peruse and interact with the nine tabletop exhibits from the presenters and suppliers.

The attendees represented by many of the major suppliers (Dow, Resolution, Bayer, Huntsman, Cognis, Air Products, CVC, Thai Epoxy, Degussa, Rebus etc.), as well as the many formulators and distributors, were all pleased with the conference program. The conference ended with a chance for attendees to play golf on the award winning Disney course, Osprey Ridge. ❖

Product Stewardship and Regulatory Affairs REPORT

by Lynne Harris, SPI

As part of a continuing update of regulations of interest to the TTD, Elizabeth King of Resolution Performance Products and a member of the Epoxy Resin Systems Task Group (ERSTG), provided an informative presentation on Waste Disposal. She briefly reviewed the EPA Resource

Conservation and Recovery Act (RCRA), discussed what a waste stream is according to EPA's 40 CFR 261.2 and .3, discussed what are solid and hazardous wastes, the various listed wastes and the characteristics of a hazardous waste. Elizabeth King also discussed practical disposal solutions, what constitutes "drum

empty and RCRA empty" and some difference between EPA and DOT on hazardous wastes.

Rob Bee, Manager of the Safety Department at Walt Disney World Resorts in Orlando gave an interesting and entertaining presentation on how a traditional Occupational Health &

Safety Program can be managed in a uniquely diverse and ever changing Resort/Theme Park setting and how the program must be modified to incorporate general liability issues associated with the guest dynamic. His presentation also touched on the application and safe use of epoxies for the Disney characters. ❖

Informative Regulatory Affairs Program Planned for Cincinnati

by Charlie Bartish, Air Products

The Product Stewardship and Regulatory Affairs team is planning another solid program for Cincinnati. The program will continue with the five-theme approach announced several years ago in San Antonio. John Phillips, Dow, will highlight company Hazards Communications requirements for the US, Canada, and in part the European Union. We are still trying to confirm a speaker from NIOSH, whose headquarters are located in Cincinnati. And of course, attendees from the Product Stewardship and Regulatory Affairs committee will be available for conversation during the tabletop session on Monday evening. ❖

Suppliers' Section Meeting

By Pete Toohey, Degussa Corporation

Ten suppliers attended the Suppliers Meeting. A number of issues were discussed, but none finalized. The following topics were covered:

1. Consider changing to a 1 conference per year format. It could encourage more attendees at a single meeting than we currently get. We did not determine whether a single meeting should be in the Spring or the Fall.

2. If going to a once-per-year meeting format, consider having 3 half days with papers, leaving the afternoons open for networking. Consider having 'split-sessions' with simultaneous sessions (e.g. epoxy, or urethane potting & casting or adhesives & coatings).

3. Announce meeting attendance and membership in TTD, perhaps in the newsletter or a press release.

4. When looking for papers for future meetings, consider contacting some of the educational communities for papers to widen the scope of what is being presented.

5. In order to increase attendance two suggestions were made. Either have a 'supplier sponsored event' or an interesting Keynote Speaker.

6. Invite people from

industry magazines for increased publicity. Their attendance could be free.

7. Consider various meeting locations again.

These suggestions were given to the Executive Committee and the Steering Committee for consideration. ❖

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